

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please cancel claims 14~23 without prejudice or disclaimer to the subject matter recited therein.

Please amend the following claim:

1. (Amended) A semiconductor package for three-dimensional mounting, comprising:

a first substrate having an upper surface on which a first metal pattern is formed and a lower surface on which a second metal pattern is formed, said first metal pattern and second metal pattern being electrically connected to each other;

a semiconductor chip which is placed on the upper surface of the first substrate and is electrically connected to the first metal pattern;

a sealing resin layer which is formed on the upper surface of the first substrate and seals the semiconductor chip and the first metal pattern;

a conductive wire which passes through the resin layer and has one end electrically connected to the first metal pattern and the other end exposed at a top surface of the resin layer, the exposed other end of said conductive wire and the top surface of the resin layer being substantially level with each other; and

a first electrode which is formed on the lower surface of the first substrate and is electrically connected to the second metal pattern.

AMENDMENT

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